

穎崴科技股份有限公司

WinWay Technology

Citi 2024 Taiwan Tech Conference

2024/06/05

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WinWay's actual results or developments may differ materially from those indicated by these forward-looking statements as a result of various factors and uncertainties, including but not limited to market demand, price fluctuations, competition, change in legal, government policies, financial market conditions, and other risks and factors beyond our control.

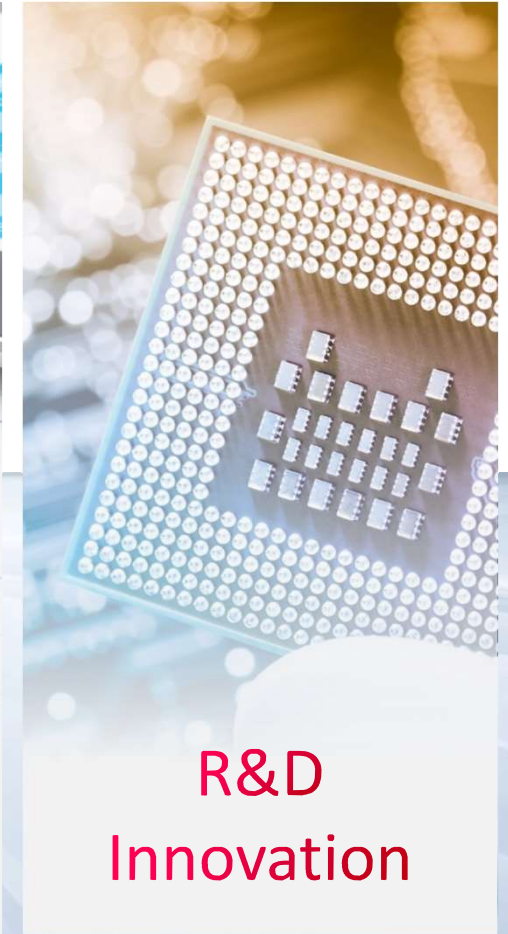
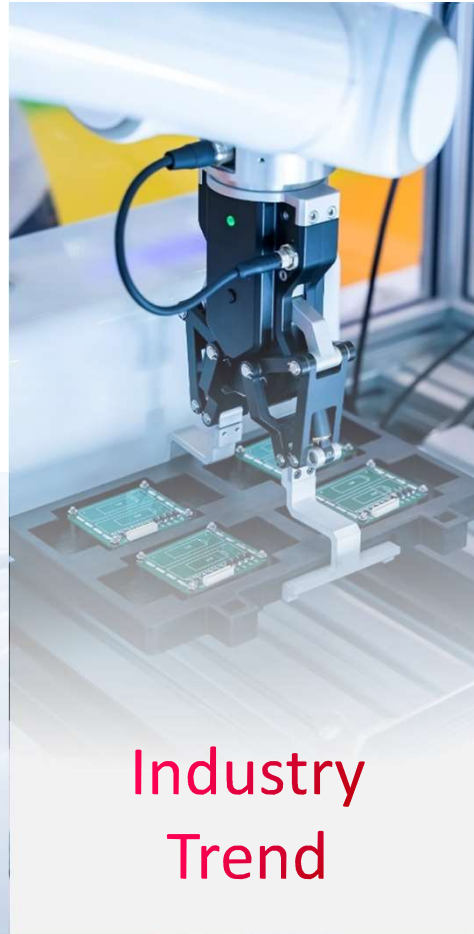
This presentation does not undertake any obligation to publicly update any forward-looking statements to reflect events or circumstances after the date on which any such statement is made or to reflect the occurrence of unanticipated events.

Company Information

Founded	2001/04 /10
Business Operation	Design, manufacture, sale and service of test interface products
Chairman & CEO	Mark Wang
Capital Stock	NTD 347,691,200
Employees	919
Registered Address	No.68, Chuangyi S. Rd, Nanzi Dist. Kaohsiung City 81156, Taiwan



Agenda



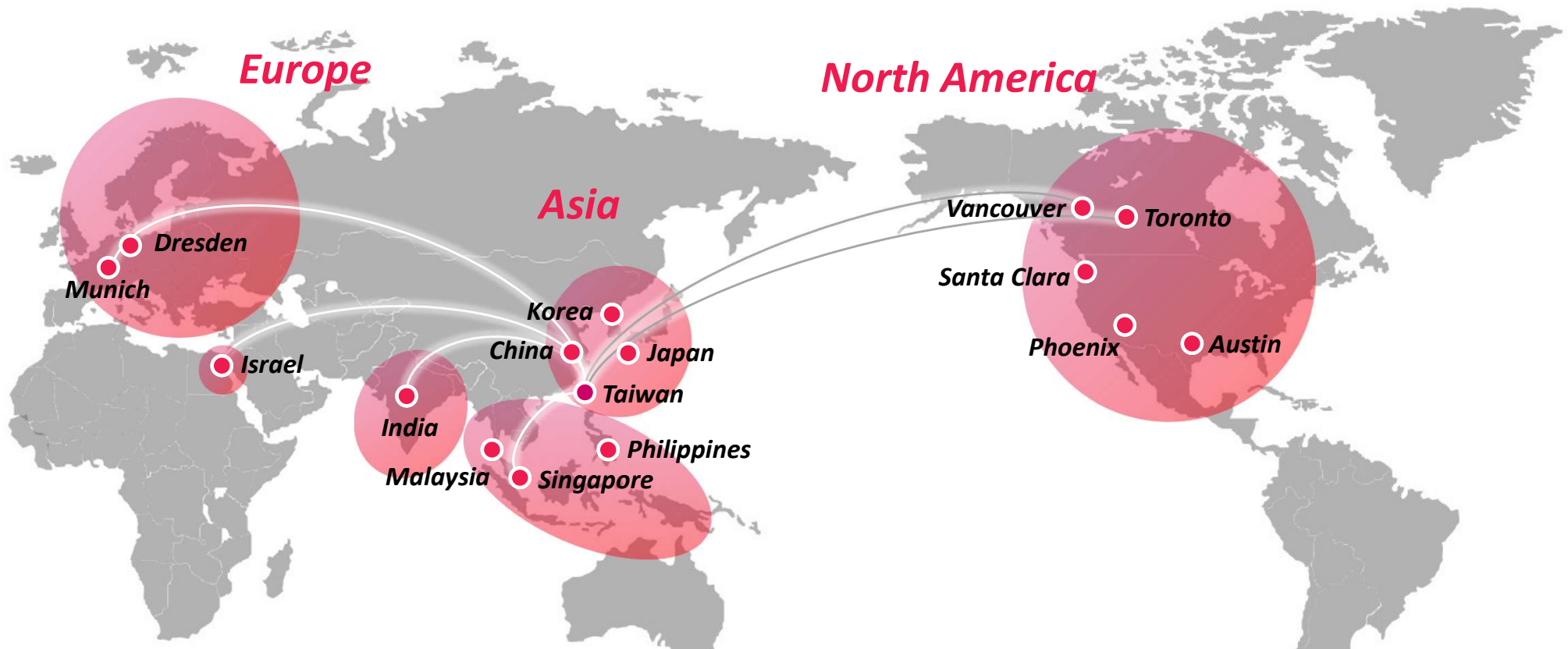
TWSE: 6515



01

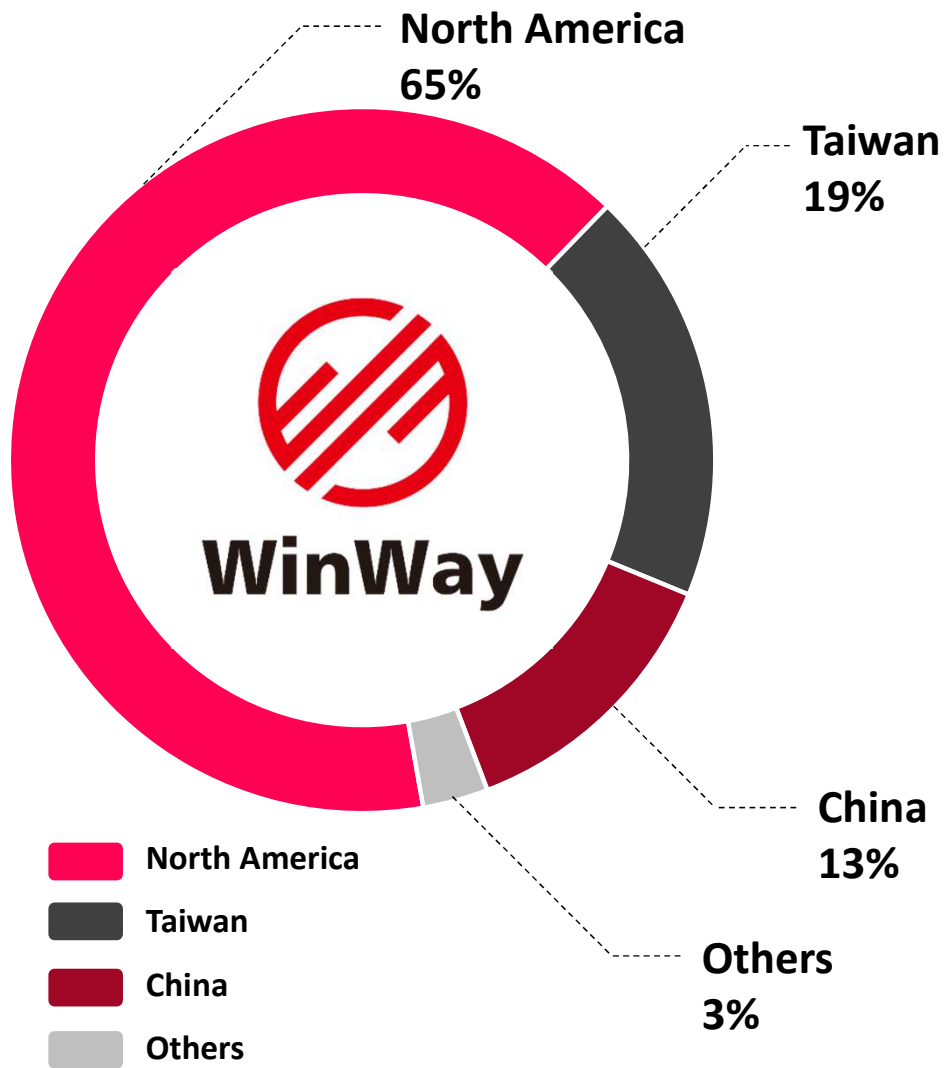
Global Presence

Global Service & Support Network



- Kaohsiung Spring Probe Plant
- Kaohsiung Plant
- Hsinchu Plant
- Suzhou Plant

Worldwide Customer



82%

Top10 IC Design

200+

Active Customers

TWSE: 6515



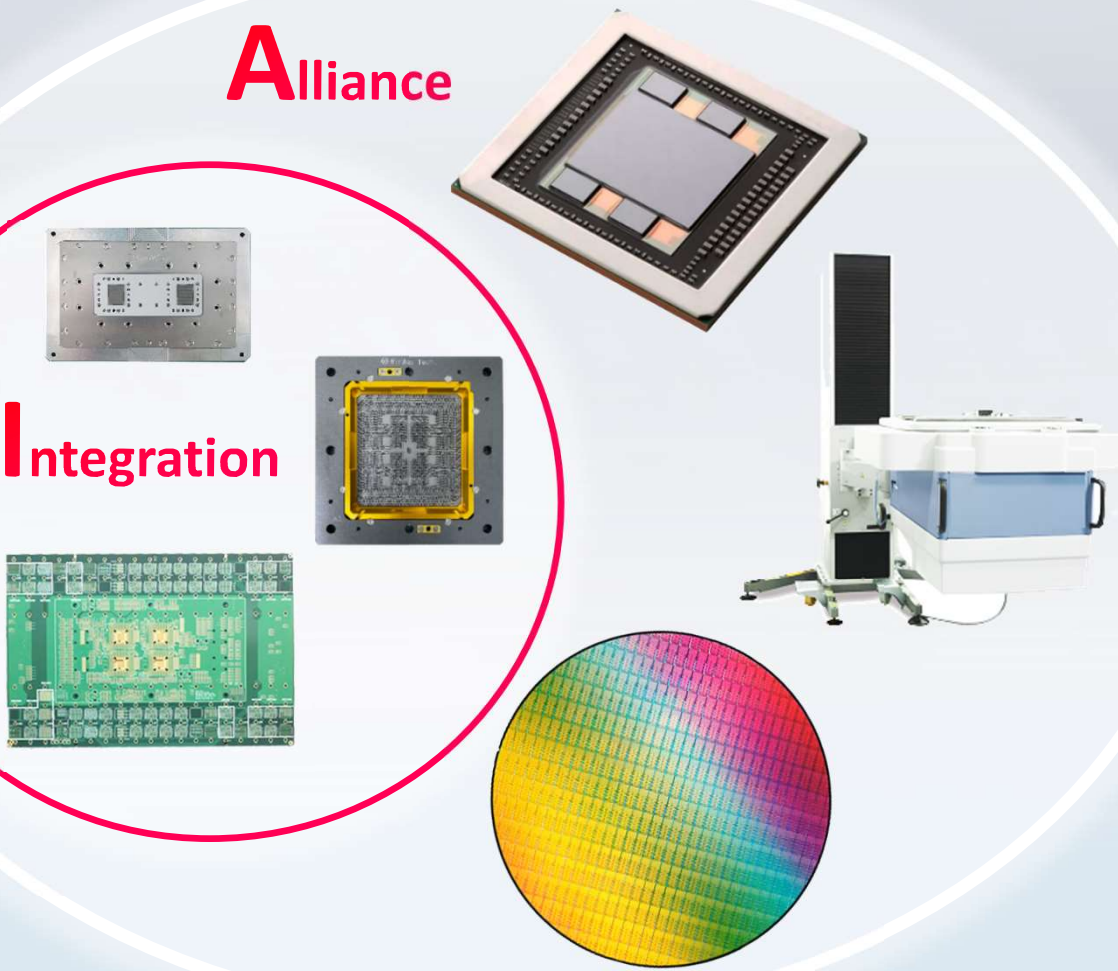
02

Industry Trend

New Opportunities in the Semiconductor Industry

Alliance

Integration



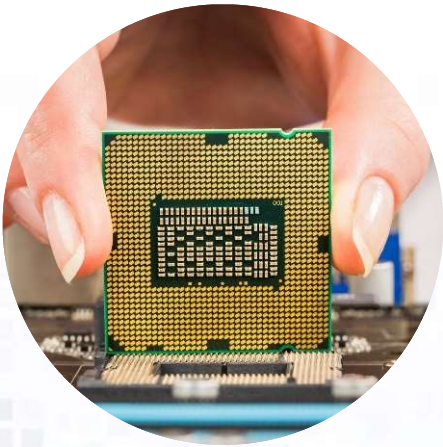
Artificial **I**ntelligence

CPU 、 GPU 、 HPC

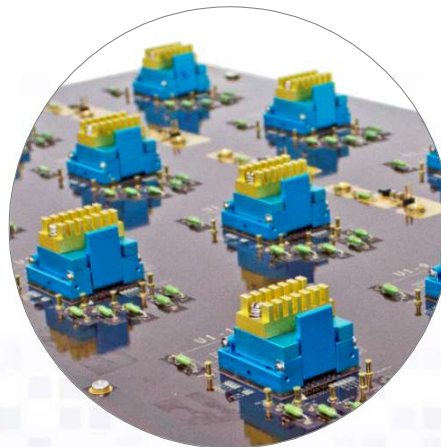


圖片來源：SEMI, Advantest

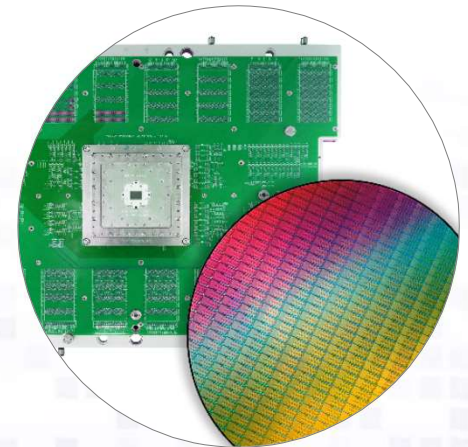
Test Interface Total Solution



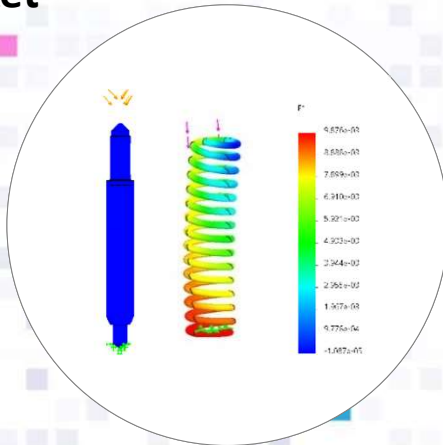
Coaxial Test Socket



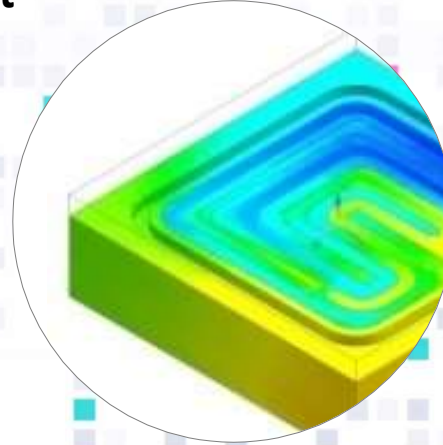
Burn-in Socket



Vertical Probe Card

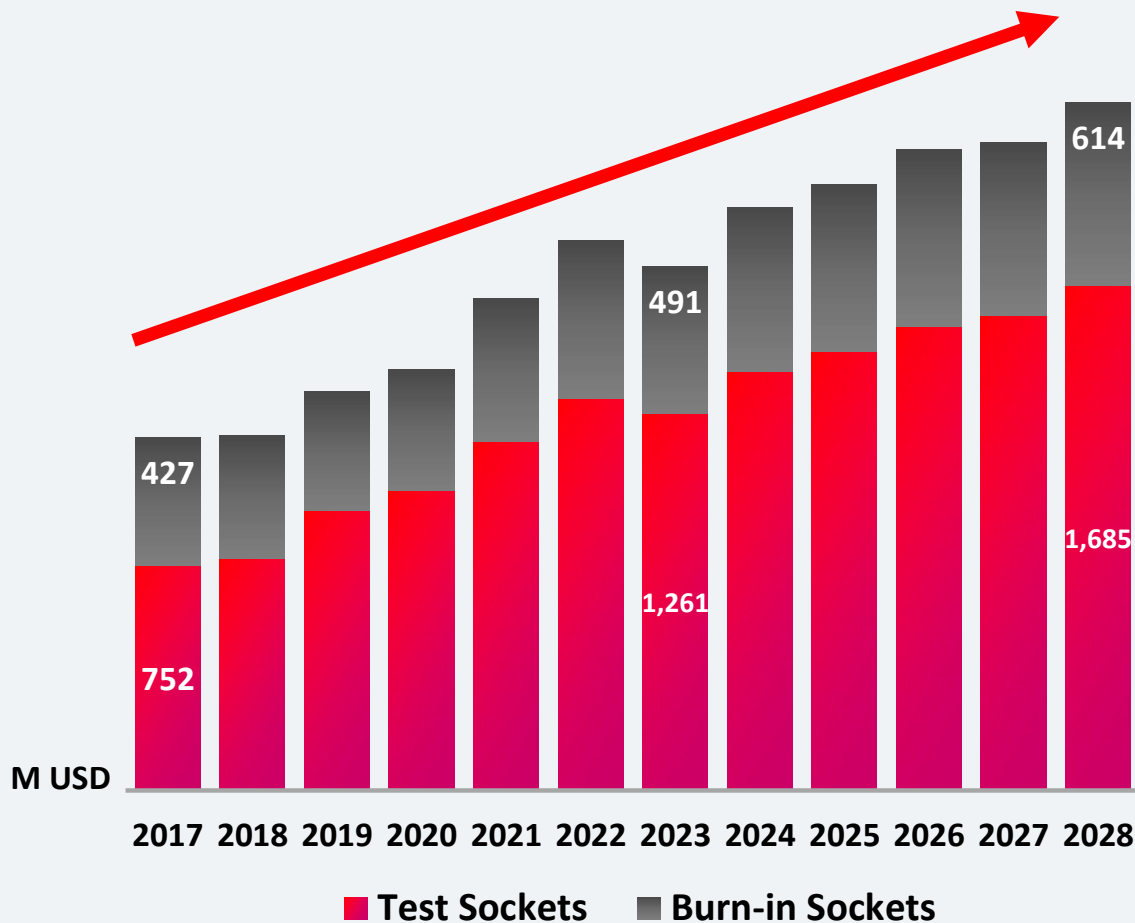


Spring Probe



Thermal Control System

Greater Need for System Level Test



SOURCE: Yole, WinWay 2023

Leadership in Semiconductor Test Interface

SOURCE: Yole Group 2024

**Test and Burn-in
Socket Ranking**
(2023)

5

**Test Socket
Ranking**
(2023)

3

**Probe Card
Ranking**
(2023)

20

TWSE: 6515



03

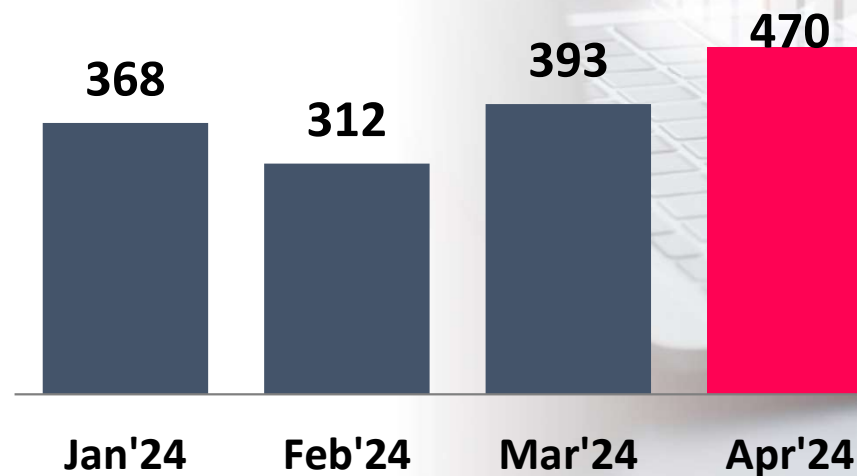
Financial Performance

Revenue Trend

QUARTERLY REVENUE (NTD MILLION)



MONTHLY REVENUE (NTD MILLION)

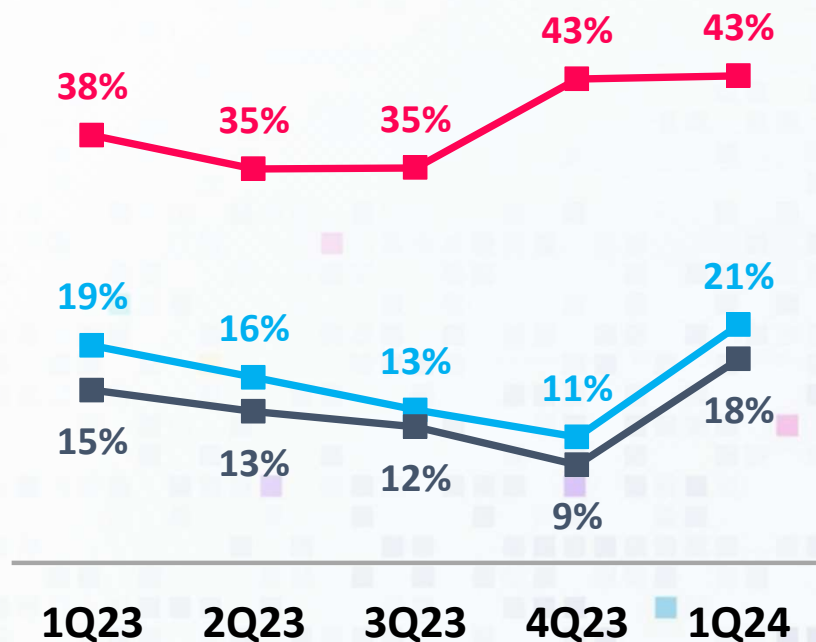


Profitability Trend

2023 EPS
(NT\$) **13.52**

Dividend
11.0

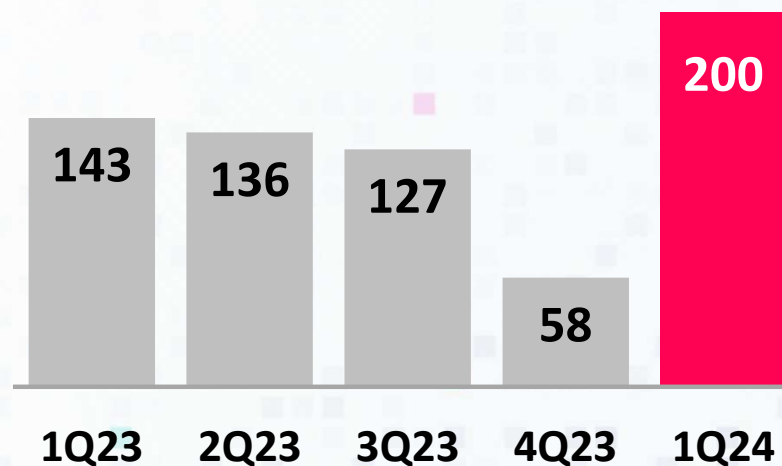
— Gross Margin — Operating Margin — Net Margin



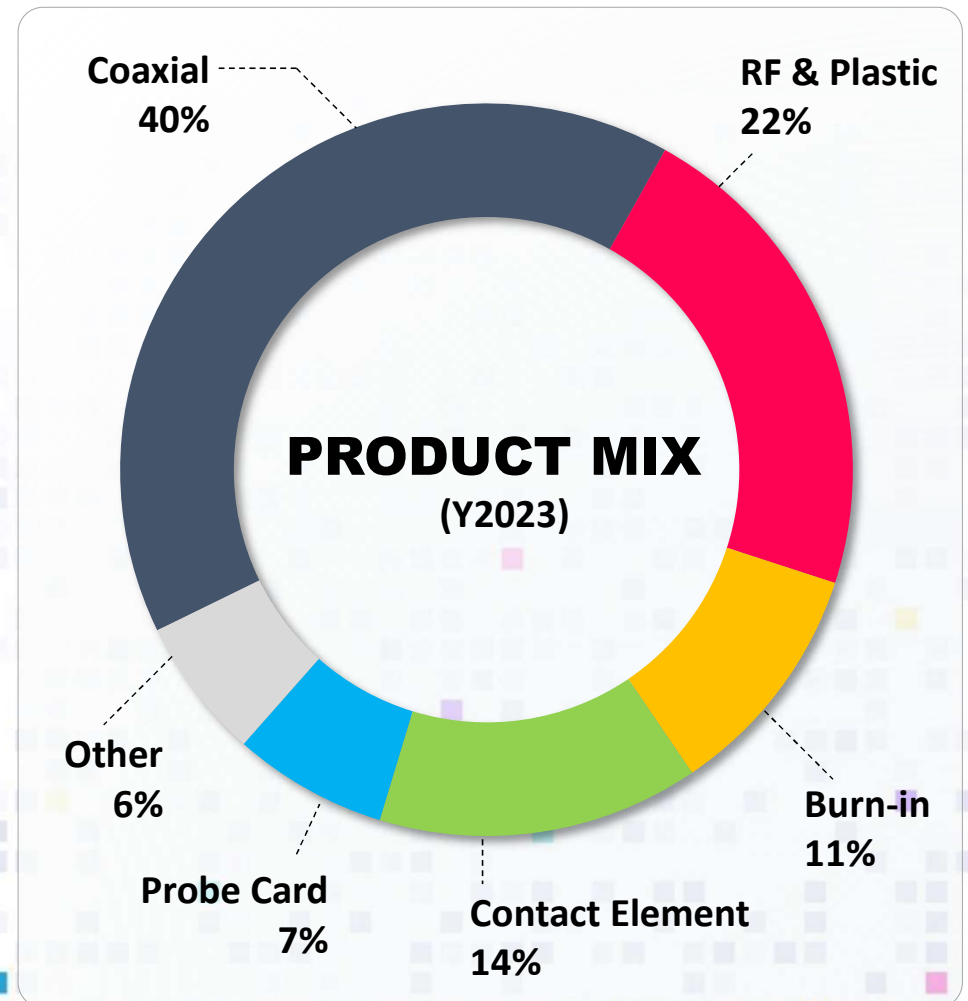
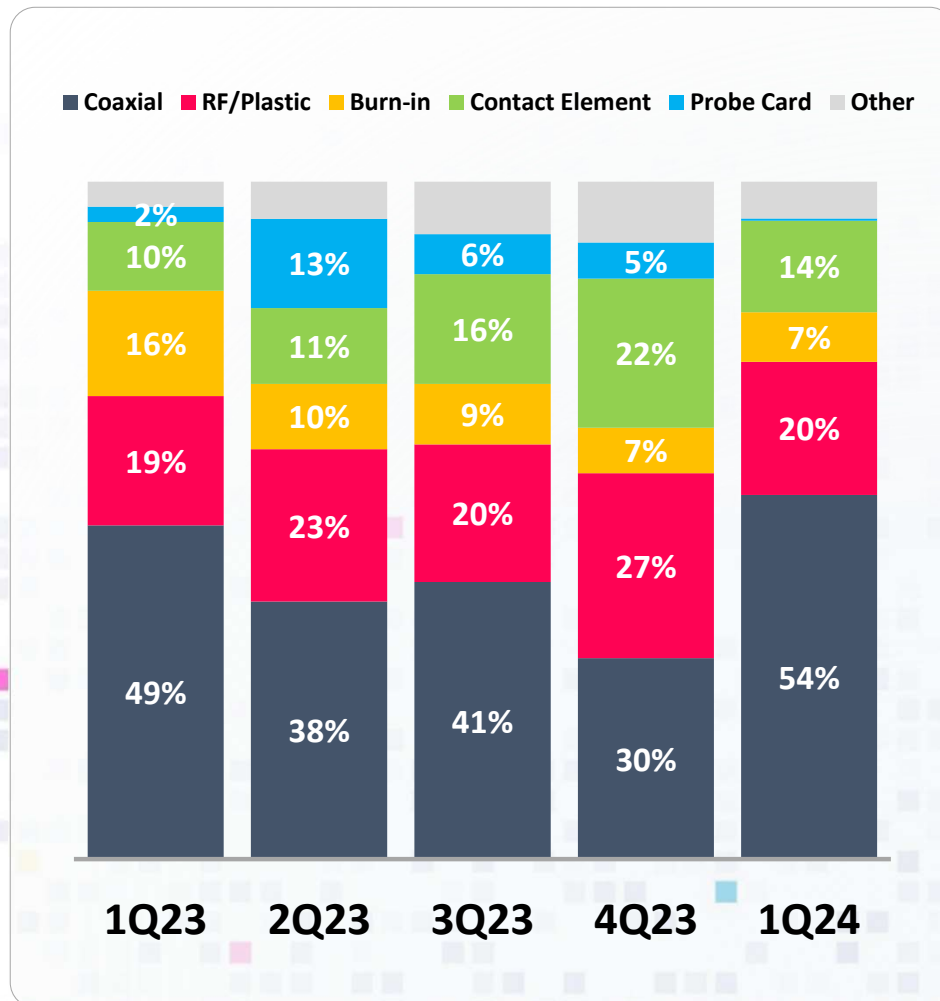
EPS (NT\$)

4.18	3.96	3.70	1.68	5.81
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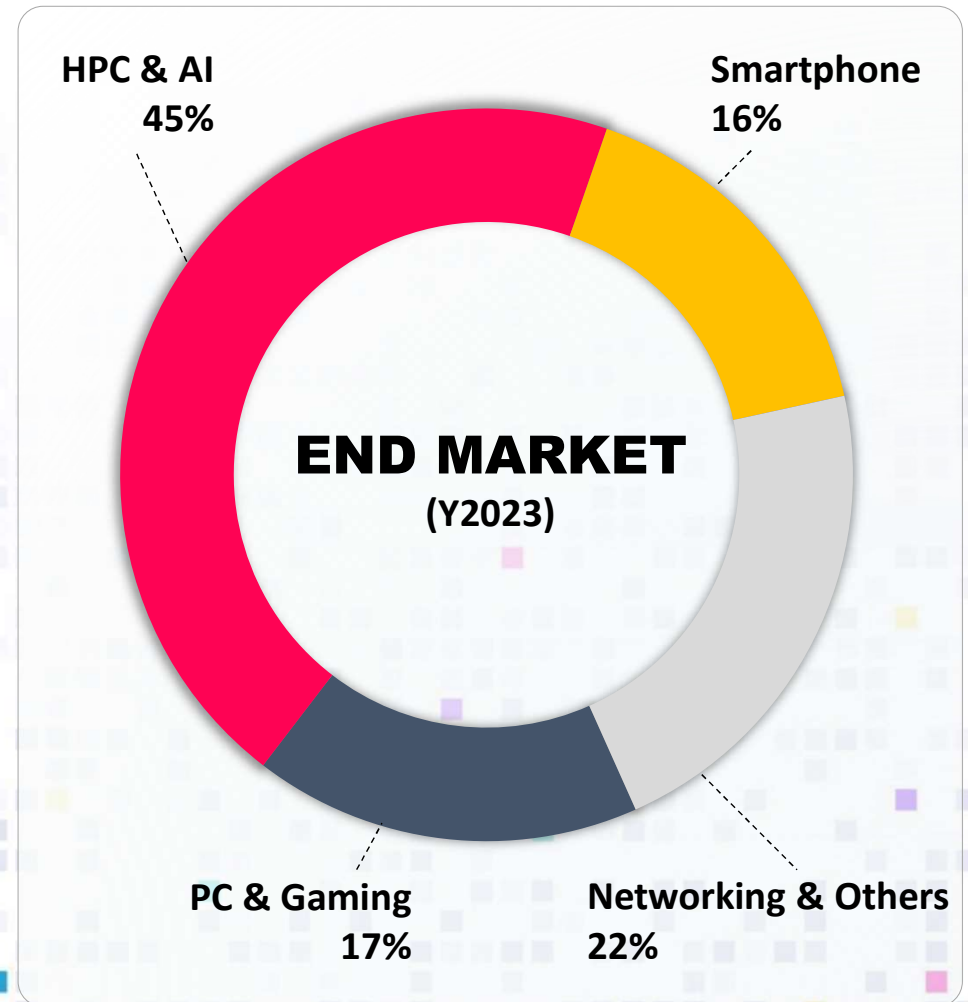
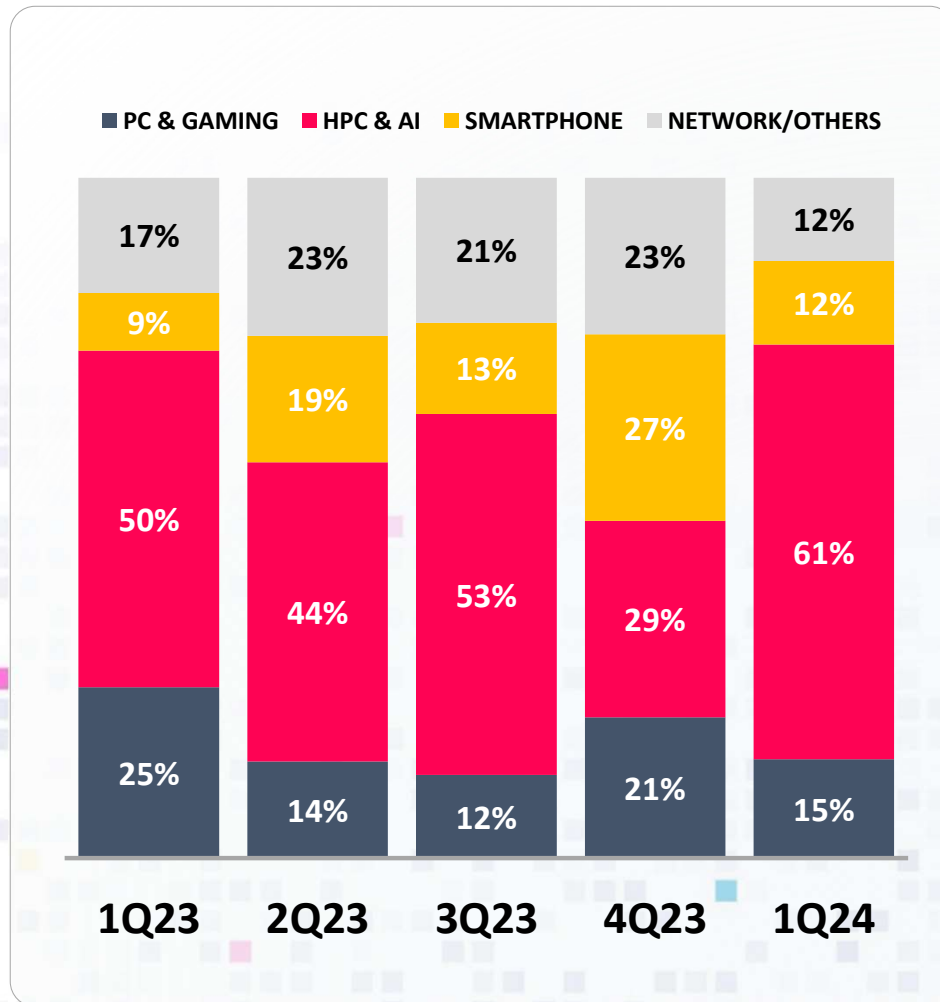
NET INCOME (NTD M)



Revenue by Product Mix



Revenue by End Market



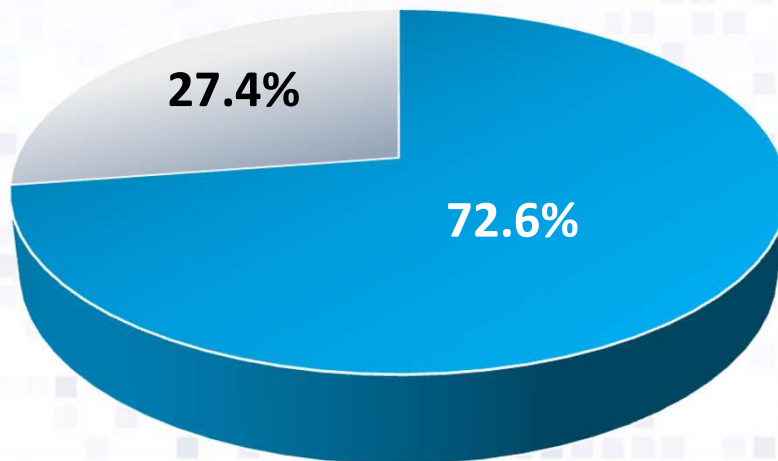
Driven by Advanced Technology

7nm (or equivalent node) and below

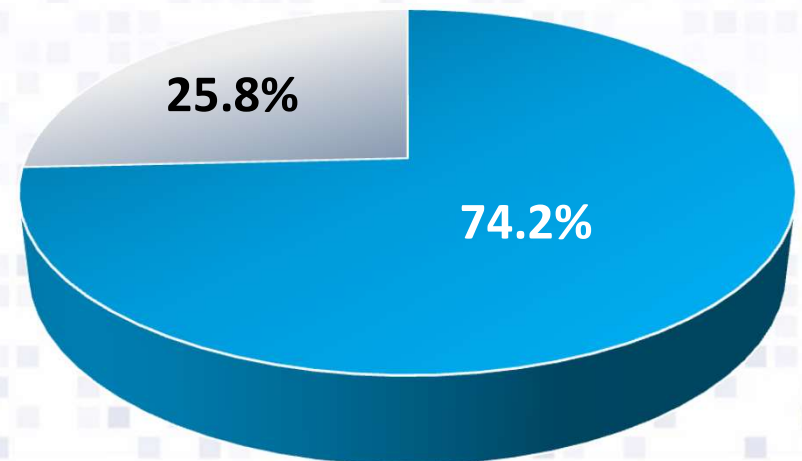
Mature Node

Advanced Node

2022



2023



04

**R&D
Innovation**

Driving Force for Future Innovation



HPC



AI



Edge Computing

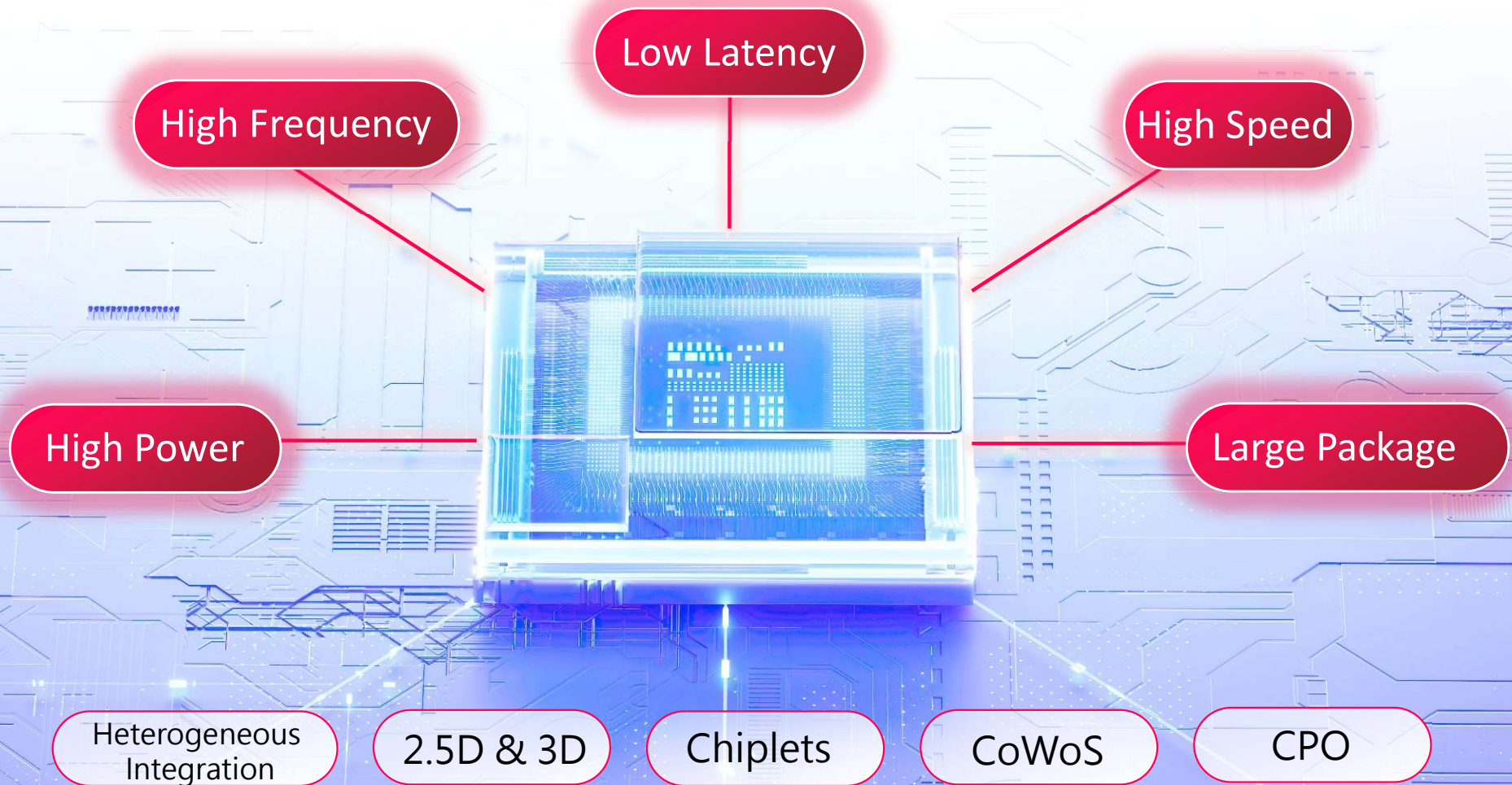


5G



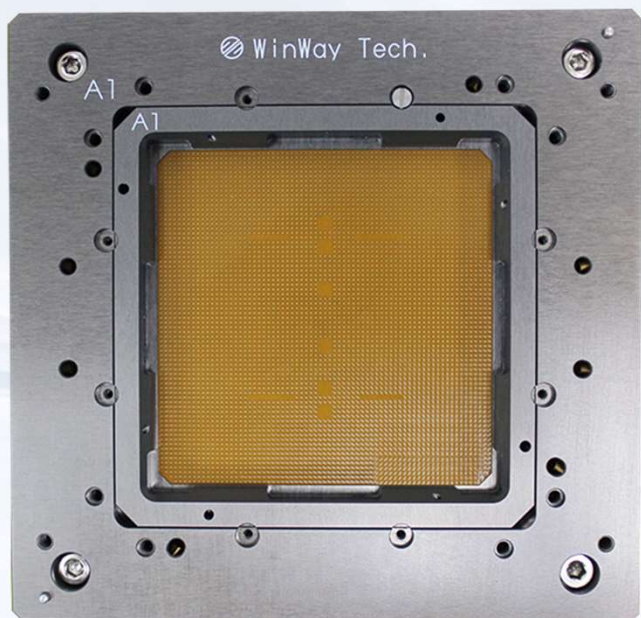
Gaming

High-Performance Testing Driven by Advanced Packaging



Introducing WinWay HyperSocket™

Patented Product



Computing

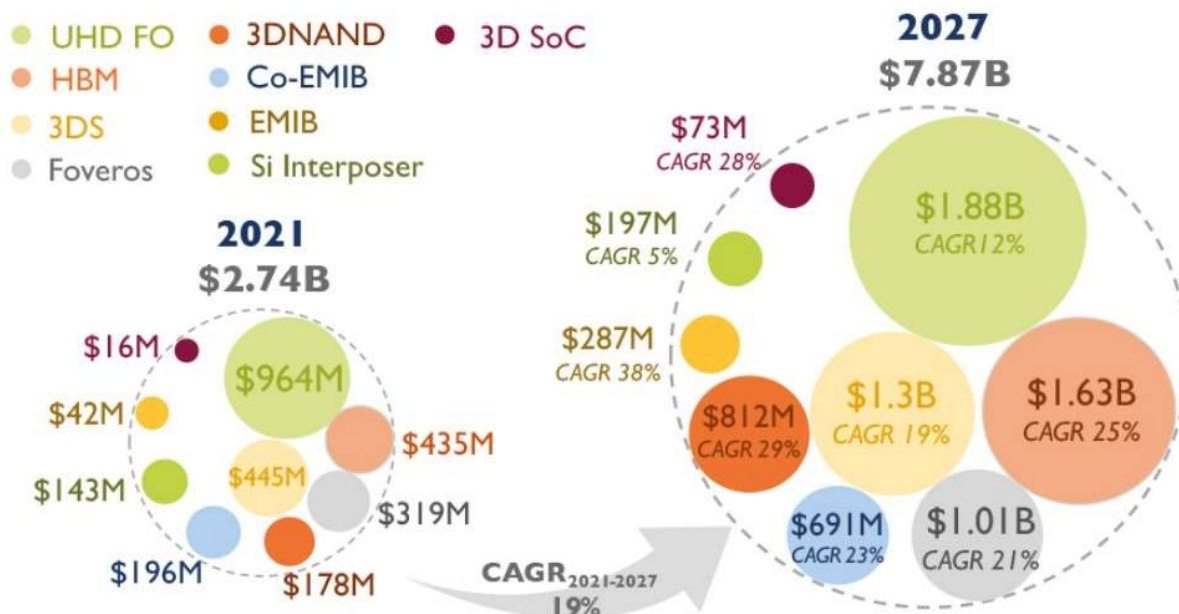
Auto

AI ASIC

VR

2021 - 2027 high-end performance packaging market size by technology

(Source: High-End Performance Packaging 2022 – Focus on 2.5D/3D Integration report, March 2022)

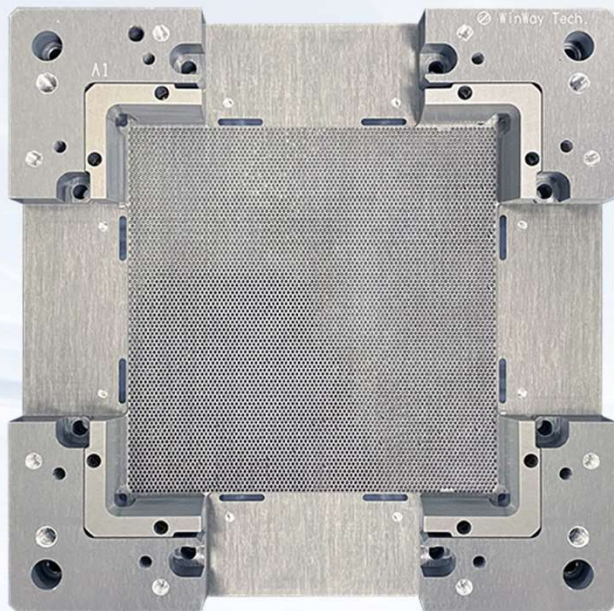


資料來源：Yole Group, 2023

Industry-Leading High Speed Test Socket

SerDes PAM4 224Gbps

Patented Product

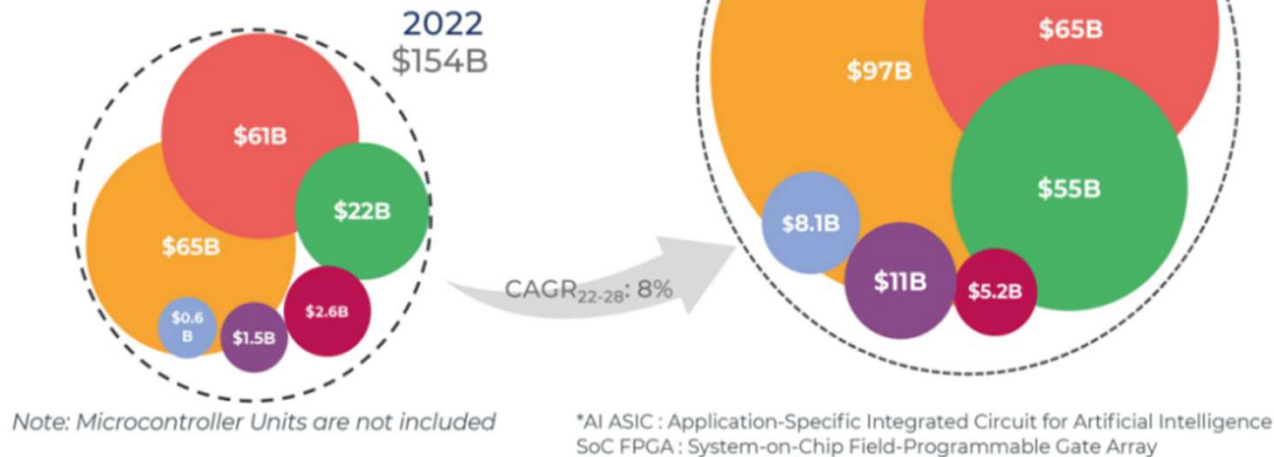


SerDes 224Gbps

PCIe Gen 7/GDDR7

All High-Speed Specifications

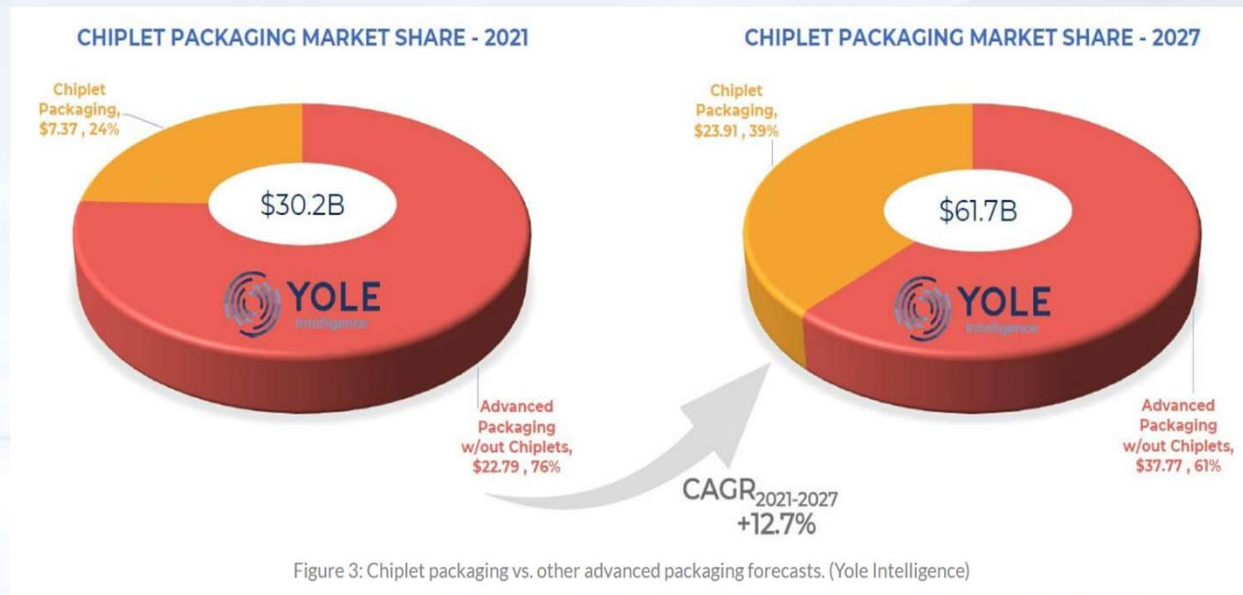
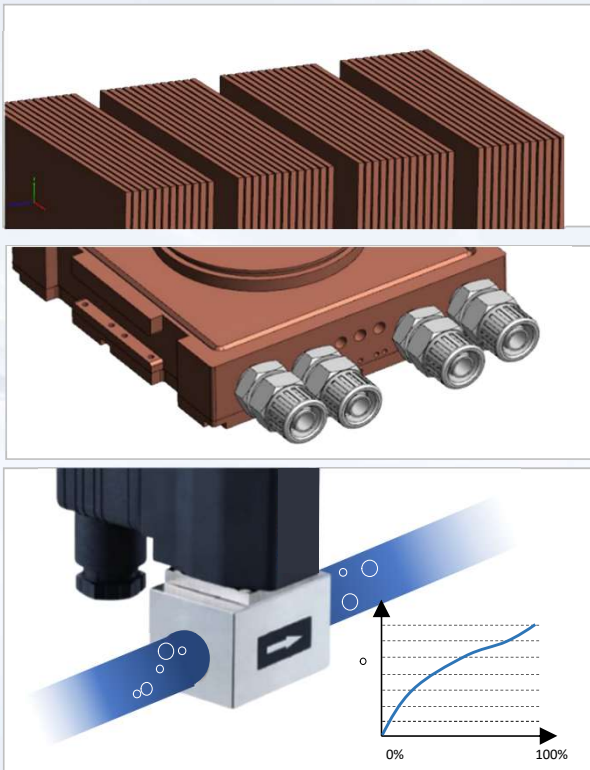
- Application Processing Unit (APU)
- Central Processing Unit (CPU)
- Graphics Processing Unit (GPU)
- Data Processing Unit (DPU)
- AI ASIC*
- SoC FPGA*



SOURCE : Yole Group, 2023

Leadership 2000W High Power Thermal HEATCon Titan

Patented Product



SOURCE : Yole Group, 2023

Chiplet/3D Package

**Address Large Package
Thermal Challenges**

**Enhanced thermal distribution
across chip package**

Introducing Integrated Wafer-Level Probing System for CPO



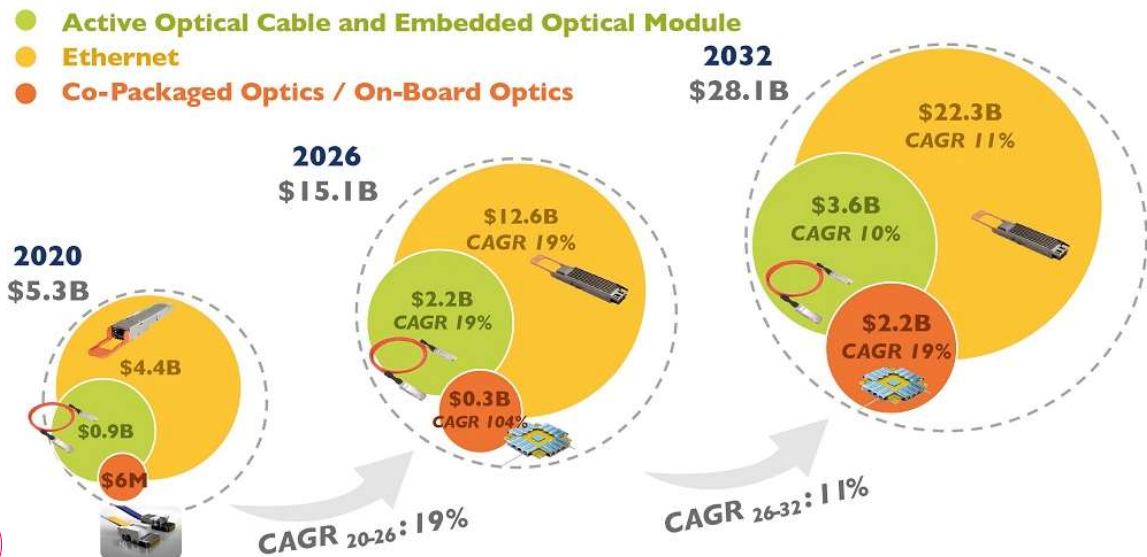
Fine-pitch, double-sided probing system

Opto-electrical testing solution

CPO for future 800G/1.6T networks

2020 vs. 2026 vs. 2032 datacom optics revenue growth forecast

(Source: Co-Packaged Optics for Data Centers 2022 report, Yole Développement, 2022)



SOURCE : Yole Group, 2023

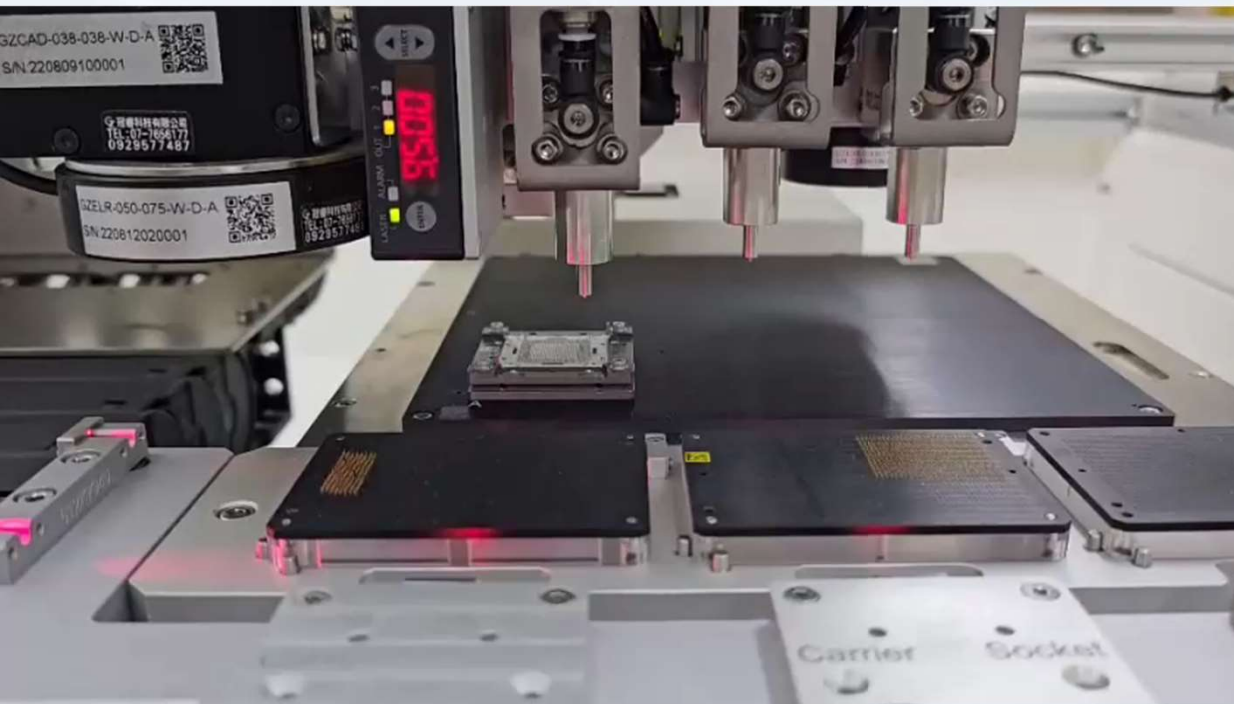
Exclusive In-House Automation Equipment

High-Speed Re-Pin System

Patented Product

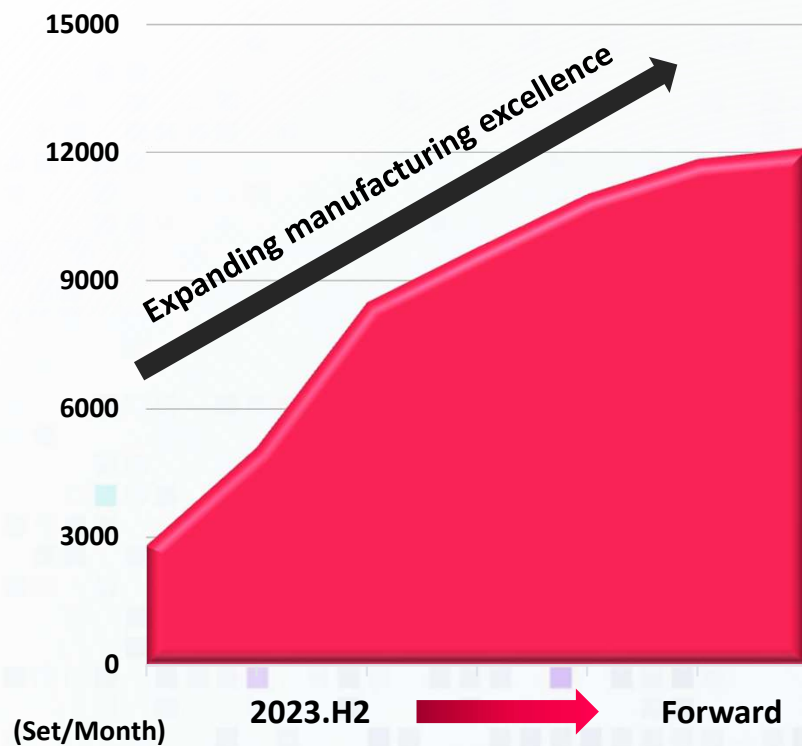
IC Design NPI

OSAT Production

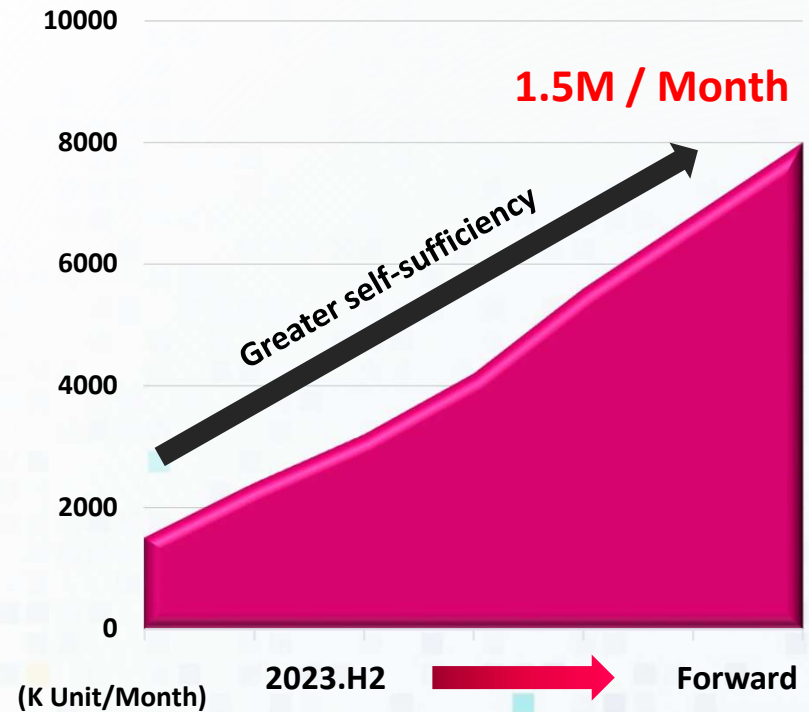


Socket & Spring Probe All in House

WW Socket Capacity (monthly)



WW Spring Probe Capacity





THANK YOU

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www.winwayglobal.com